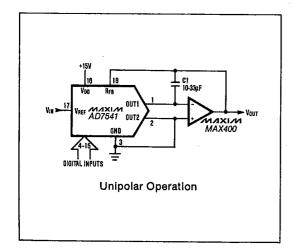
Wafer level laser trimmed thin-film resistors and temperature compensated NMOS switches assure true 12-bit performance over the full operating temperature range. In addition, all digital inputs are compatible with both CMOS and TTL logic levels.

Maxim's AD7541 is electrically and pin compatible with the Analog Devices AD7541. It is available in standard width 18-lead DIP and Small Outline (SO) packages.

#### **Applications**

Machine and Motion Control Systems Automatic Test Equipment μP Controlled Calibration Circuitry Programmable Gain Amplifiers **Digitally Controlled Filters Programmable Power Supplies** 

### Typical Operating Circuit



MAXIM is a registered trademark of Maxim Integrated Products

### **Features** T-51-09-12

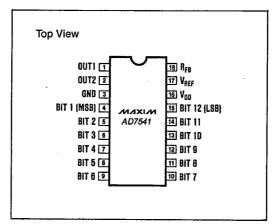
- ◆ 12 Bit Linearity (1/2 LSB)
- 1 LSB Gain Accuracy
- Guaranteed Monotonic
- **♦ Low Power Consumption**
- ♦ Four-Quadrant Multiplication
- ◆ TTL and CMOS Compatible
- ♦ Pin-For-Pin Second Source

### Ordering Information

PART	TEMP. RANGE	PACKAGE*	ERROR
AD7541JN	0°C to +70°C	Plastic DIP	1 LSB
AD7541KN	0°C to +70°C	Plastic DIP	½ LSB
AD7541JCWN	0°C to +70°C	Small Outline	1 LSB
AD7541KCWN	0°C to +70°C	Small Outline	1/2 LSB
AD7541JC/D	0°C to +70°C	Dice	1 LSB
AD7541AQ	-25°C to +85°C	CERDIP**	1 LSB
AD7541BQ	-25°C to +85°C	CERDIP**	½ LSB
AD7541AD	-25°C to +85°C	Ceramic	1 LSB
AD7541BD	-25°C to +85°C	Ceramic	½ LSB
AD7541SQ	-55°C to +125°C	CERDIP**	1 LSB
AD7541TQ	-55°C to +125°C	CERDIP**	1/2 LSB
AD7541SD	-55°C to +125°C	Ceramic	1 LSB
AD7541TD	-55°C to +125°C	Ceramic	½ LSB

All devices — 18 lead package.

### Pin Configuration



MIXIM

Maxim Integrated Products 2-75

Maxim reserves the right to ship Ceramic packages in lieu of CERDIP packages.

T-51-09-12

### **CMOS 12 Bit** Multiplying D/A Converter

### **ABSOLUTE MAXIMUM RATINGS**

13E D

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum ratings conditions for extended periods may affect the device reliability.

### **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, V<sub>DD</sub> = +15V, V<sub>REF</sub> = +10V, V<sub>OUT1</sub> = V<sub>OUT2</sub> = GND, unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP	MAX.	UNITS
DC ACCURACY						
Resolution	1		12			Bits
Nonlinearity		AD7541J/A/S (Note 2) AD7541K/B/T (Note 3)	±1 ±0.5			LSB
Gain Error (Note 4)		Using R <sub>FB;</sub> T <sub>A</sub> = +25°C T <sub>MIN</sub> to T <sub>MAX</sub>			±12.5 ±16.7	LSB
Power Supply Rejection	PSRR	V <sub>DD</sub> = +14.5V to +15.5V; T <sub>A</sub> = 25°C T <sub>MIN</sub> to T <sub>MAX</sub>			0.01 0.02	%/%V <sub>DD</sub>
Output Leakage Current		V <sub>REF</sub> = ±10V; T <sub>A</sub> = +25°C T <sub>MIN</sub> to T <sub>MAX</sub>			±50 ±200	nĄ
Reference Input Resistance	R <sub>REF</sub>	T <sub>A</sub> = 25°C	5		20	kΩ
DYNAMIC PERFORMANCE (No	te 5)		· · · · · ·			<del>,</del>
Output Current Settling Time		To 1/2LSB			1	μ8
Feedthrough Error	1	V <sub>REF</sub> = 20V <sub>P-P</sub> at 10kHz			1	mV <sub>P-P</sub>
DIGITAL INPUTS	<u> </u>			4		
Logic HIGH Threshold	V <sub>INH</sub>		+2,4			V
Logic LOW Threshold	VINL				+0.8	V
Input Leakage Current		Digital Inputs = 0V or V <sub>DD</sub>			±1	μA
Input Capacitance	CiN	(Note 5)			. 8	pF
Input Coding		Binary, Offset Binary				<u> </u>
ANALOG OUTPUTS						<del>,</del>
Output Capacitance (Note 5) Cout Digital Inputs = V <sub>INL</sub> OUT		Digital Inputs = V <sub>INH</sub> OUT1 OUT2 Digital Inputs = V <sub>INL</sub> OUT1 OUT2			200 60 60 200	pF
POWER REQUIREMENTS	<u> </u>					- <sub>1</sub>
Operating Supply Range	VDD	Accuracy Not Guaranteed	+5		+16	V
Power Supply Current	IDD	Digital Inputs = VINH or VINL			2	mA

		the current is limited to 30mA or less.

Note 2: AD7541J/A/S are monotonic to 11 bits.

Note 3: AD7541J/A/S are monotonic to 12 bits.

Note 4: Maximum gain change from +25°C to T<sub>MIN</sub> or T<sub>MAX</sub> is ±4.2 LSBs using internal feedback resistor.

Note 5: Guaranteed by design but not 100% tested.

# AD

### CMOS 12 Bit Multiplying D/A Converter

### **Detailed Description**

13E D

The basic AD7541 DAC circuit consists of a laser-trimmed, thin-film R-2R resistor array with NMOS current switches as shown in Figure 1. Binarily weighted currents are switched to either OUT1 or OUT2 depending on the status of each input bit. Most applications require only an output op-amp and reference source. The  $V_{\rm REF}$  input accepts a wide range of signals including fixed and time varying voltage or current inputs.

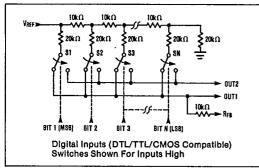


Figure 1. AD7541 Functional Diagram

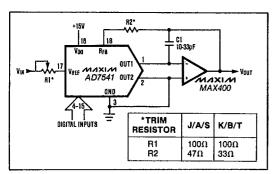


Figure 2. Unipolar Binary Operation

### Table 1. Code Table — Unipolar Binary

	OLTAL INDI		
MSB	GITAL INP	LSB	ANALOG OUTPUT
1111	1111	1111	$-V_{REF} \left( \frac{4095}{4096} \right)$
1 0 0 0	0 0 0 0	0000	$-V_{REF} \left( \frac{2048}{4096} \right) = -1/2V_{REF}$
0 0 0 0	0 0 0 0	0001	$-V_{REF}\left(\frac{1}{4096}\right)$
0000	0000	0000	ov

# Application Information Unipolar Operation

The most common configuration for the AD7541 is shown in Figure 2. The circuit is used for unipolar binary operation and/or 2-quadrant multiplication. The code table is given in Table 1. Note that the polarity of the output is the inverse of the reference input.

In many applications, gain adjustment of the AD7541 will not be necessary. In those cases, and also when gain is trimmed but only at the reference source, resistors R1 and R2 in Figure 2 can be omitted. However, if the trims are required and the DAC is to operate over a wide temperature range, then low tempco (<300ppm/°C) resistors should be used at R1 and R2.

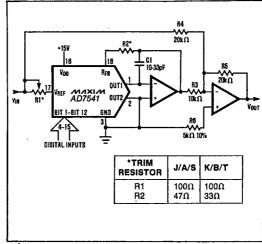


Figure 3. Bipolar Operation (4-Quadrant Multiplication)

## Table 2. Code Table — Bipolar (Offset Binary) Operation

N	ISE	3	DIGITAL INPUT LSB				В	ANALOG OUTPUT				
1	1	1	1	1	1	1	1	1	1	1	1	+V <sub>REF</sub> (2047)
1	0	0	0	0	0	0	0	0	0	0	1	$+V_{REF}\left(\frac{1}{2048}\right)$
1	0	0	0	0	0	0	0	0	0	0	0	ov
0	1	1	1	1	1	1	1	1	1	1	1	$-V_{REF}\left(\frac{1}{2048}\right)$
0	0	0	0	0	0	0	0	0	0	0	0	$-V_{REF} \left( \frac{2048}{2048} \right)$



### **CMOS 12 Bit** Multiplying D/A Converter

### **Bipolar Operation**

Bipolar, or four-quadrant, operation is shown in Figure 3. A second amplifier and three matched resistors are required. Matching to 0.01% is recommended for 12 bit performance. The code table for the output, which is "offset binary", is listed in Table 2. In multiplying applications, the MSB determines output polarity while the other 11 bits control applitude. amplitude.

### **Output Amplifier Offset**

For best linearity, OUT1 and OUT2 should be terminated at exactly 0V. In most applications, OUT1 is connected to the summing junction of an inverting op-amp. The amplifier's offset voltage can degrade the linearity of the DAC by causing OUT1 to be terminated to a non-zero voltage. The resulting error is typically 4/3Vos to 2Vos, a change of 2/3Vos. An amplifier with 3mV of offset will therefore degrade the linearity by 2mV, almost a full LSB with a 10V reference voltage. For best linearity, a low-offset amplifier such as the MAX400 should be used, or the amplifier offset must be trimmed to zero. A good rule of thumb is that Vos should be no more than 1/10 of an LSB's value. For best linearity, OUT1 and OUT2 should be termin-

An output amplifier's input bias current (IB) can also limit the DAC's performance since I<sub>B</sub> x R<sub>FB</sub> generates an offset error. I<sub>B</sub> should therefore be much less than the DAC output current for 1 LSB, typically 250nA with VREF = 10V. One tenth of this value, 25nA, is recommended. Offset and linearity can also be impaired if the output amplifier's noninverting input is grounded through a "bias current compensation resistor." This resistor adds to the offset at this pin and should not be used.

#### **Dynamic Considerations**

In static or DC applications, the AC characteristics of the output amplifier are not critical. In higher speed applications, where either the reference input is an AC signal or the DAC output must quickly settle to a new programmed value, the AC parameters of the output op-amp must be considered.

Another error source in dynamic applications is parasitic coupling of signal from the V<sub>REF</sub> terminal to OUT1 or OUT2. This is normally a function of board layout and package lead-to-lead capacitance. Signals can also be injected into the DAC outputs when the digital inputs are switched. This digital feedthrough is mostly dependent on circuit board layout and onchip capacitive coupling. Layout induced feedthrough can be minimized with guard traces between digital inputs, V<sub>REF</sub>, and the DAC outputs.

#### Compensation

A compensation capacitor, C1, may be needed when the DAC is used with a high speed output amplifier. The purpose of the capacitor is to cancel the pole formed by the DAC's output capacitance and internal feedback resistance. Its value depends on the type of op-amp used but typical values range from 10 to 33pF. Too small a value causes output ringing while excess capacitance overdamps the output. The size of C1 can be minimized, and output settling performance improved, by keeping the PC board trace and stray capacitance at OUT1 as small as possible.

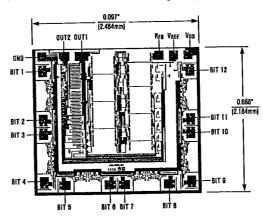
### **Grounding and Bypassing**

Since OUT1, OUT2 and the output amp's noninverting input are sensitive to offset voltages, nodes that are to be grounded should be connected directly to "single point" ground through a separate, very low resistance (less than  $0.2\Omega$ ) path. The current at OUT1 and OUT2 varies with input code creating a code dependent error if these terminals are connected to ground (or a virtual ground) through a resistive path.

A  $1\mu F$  bypass capacitor, in parallel with a  $0.01\mu F$ ceramic cap, should be connected as close to the DAC's VDD and GND pins as possible.

The AD7541 has high-impedance digital inputs. To minimize noise pick-up, they should be tied to either VDD or GND when not used. It is also good practice to connect active inputs to VDD or GND through high valued registers (1440) to receive the property of the content of the high valued resistors (1M $\Omega$ ) to prevent static charge accumulation if these pins are left floating, such as when a circuit card is left unconnected.

### Chip Topography



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